

DIALOG(R)File 352:Derwent WPI

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0007126766 - Drawing available

WPI ACC NO: 1995-158503/

XRAM Acc No: C1995-073190

XRPX Acc No: N1995-124616

Multilayer packaging material with improved hot water resistance - composed of intermediate layer of saponified ethylene!-vinyl! ester! copolymer and polyamide

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Patent Family (2 patents, 1 countries)

Patent	Application					
Number	Kind	Date	Number	Kind	Date	Update
JP 7081004	A	19950328	JP 1994167583	A	19940720	199521 B
JP 3310464	B2	20020805	JP 1994167583	A	19940720	200258 E

Priority Applications (no., kind, date): JP 1993180141 A 19930721

Patent Details

Number	Kind	Lan	Pg	Dwg	Filing Notes
JP 7081004	A	JA	8	0	
JP 3310464	B2	JA	8		Previously issued patent JP 07081004

Alerting Abstract JP A

The material comprises: (1) a resin outer layer having a moisture permeability of 40 g/m²/day or higher (measured at 40 deg. C. and 90 % RH); (2) a compsn. layer; and (3) a resin inner layer. (2) is made from: (A) 96-51 wt. % of a saponified ethylene-vinylester copolymer, and 4-49 wt. % of (B) a polyamide and (C) a polyamide of a type different from (B) and having a solubility parameter different from that of the absolute value of $(Sp(B)-Sp(C)) = 0.05-2$. (I) and the absolute value of $(Sp(A)-Sp(C))$ - the absolute value of $(Sp(A)-Sp(C))$ is more than zero. (II). The wt. ratio of (B):(C) is 97:3-55:45. The resin inner layer has a moisture permeability of 40 g/m²/day or

lower (measured at 40 deg. C. and 90 % RH). In (I) and (II), Sp(A), Sp(B), and Sp(C) are the solubility parameters of components (A), (B) and (C) respectively.

Also claimed is the multilayer packaging material in which the compsn. layer (2) is the outer layer and a resin inner layer (3) having a moisture permeability of 20 g/m²/day or lower is included.

USE/ADVANTAGE - Used for retort food packagings. The material has improved hot water resistance, no re-whitening on water contact or high moisture environment after retorting.

Title Terms /Index Terms/Additional Words: MULTILAYER; PACKAGE; MATERIAL; IMPROVE; HOT; WATER; RESISTANCE; COMPOSE; INTERMEDIATE; LAYER; SAPONIFICATION; POLYETHYLENE; POLYVINYL; POLYESTER; COPOLYMER; POLYAMIDE

Class Codes

International Classification (Main): B32B-027/08, B32B-027/28
(Additional/Secondary): B32B-027/34, B65D-065/40, C08L-023/26, C08L-077/00

File Segment: CPI; EngPI

DWPI Class: A18; A92; P73; Q34

Manual Codes (CPI/A-M): A05-F01E; A07-A04E; A09-A09; A10-E09; A12-P01

Chemical Indexing

Specific Compound Numbers: R00326

Derwent Chemistry Resource Numbers: (Linked) 1013-DIS; 1013

Key Word Indexing

1 1013-DIS

Polymer Indexing

<01>
001 017; G0566-R G0022 D01 D12 D10 D51 D53 D58 D63 F41; G0044 G0033
G0022
D01 D02 D12 D10 D51 D53 D58 D82 R00326-R 1013-R; H0022 H0011; P1332
P1694; P1730 P1694 D01; S9999 S1285-R; P1150
002 017; ND01; K9745-R; Q9999 Q8366-R; K9574 K9483; K9698 K9676; B9999

B5447 B5414 B5403 B5276; Q9999 Q6780; Q9999 Q7589-R; B9999 B4682
B4568; B9999 B4706-R B4568; B9999 B4262 B4240

<02>

001 017; ND01; K9574 K9483; K9698 K9676; K9712 K9676; Q9999 Q7589-R;
Q9999 Q8366-R; B9999 B4875 B4853 B4740

<03>

001 017; P0635-R F70 D01; S9999 S1285-R

002 017; ND01; K9745-R; Q9999 Q8366-R; K9574 K9483; K9698 K9676; B9999
B5447 B5414 B5403 B5276; Q9999 Q6780; Q9999 Q7589-R; B9999 B4682
B4568; B9999 B4706-R B4568; B9999 B4262 B4240

003 017; B9999 B3510-R B3372

Original Publication Data by Authority

Japan

Publication No. JP 7081004 A (Update 199521 B)

Publication Date: 19950328

****MULTILAYERED PACKAGING BODY****

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Language: JA (8 pages, 0 drawings)

Application: JP 1994167583 A 19940720 (Local application)

Priority: JP 1993180141 A 19930721

Original IPC: C08L-23/26(-) C08L-77/00(-) B32B-27/08(A) B32B-27/28(B)
B65D-65/40(B)

Current IPC: C08L-23/26(-) C08L-77/00(-) B32B-27/08(A) B32B-27/28(B)
B65D-65/40(B)

Publication No. JP 3310464 B2 (Update 200258 E)

Publication Date: 20020805

Language: JA (8 pages)

Application: JP 1994167583 A 19940720 (Local application)

Priority: JP 1993180141 A 19930721

Related Publication: JP 07081004 A (Previously issued patent)

Original IPC: B32B-27/28(A) B32B-27/34(B)

Current IPC: B32B-27/28(A) B32B-27/34(B)